SDAS276A - DECEMBER 1994 - REVISED JULY 2000

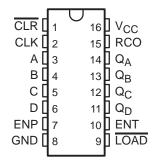
- **Internal Look-Ahead Circuitry for Fast** Counting
- Carry Output for n-Bit Cascading
- **Synchronous Counting**
- Synchronously Programmable
- **Package Options Include Plastic** Small-Outline (D) and Shrink Small-Outline (DB) Packages, Ceramic Chip Carriers (FK), Standard Plastic (N) and Ceramic (J) DIPs

description

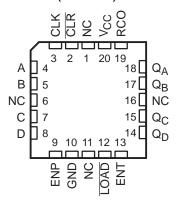
These synchronous, presettable, 4-bit decade and binary counters feature an internal carry look-ahead circuitry for application in high-speed counting designs. The SN54ALS162B is a 4-bit decade counter. The 'ALS161B, 'ALS163B, 'AS161, and 'AS163 devices are 4-bit binary counters. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincidentally with each other when instructed by the count-enable (ENP, ENT) inputs and internal gating. This mode of operation eliminates the output counting spikes normally associated with asynchronous (ripple-clock) counters. A buffered clock (CLK) input triggers the four flip-flops on the rising (positive-going) edge of the clock input waveform.

These counters are fully programmable; they can be preset to any number between 0 and 9 or 15. Because presetting is synchronous, setting up a low level at the load (LOAD) input disables the counter and causes the outputs to agree with the setup data after the next clock pulse, regardless of the levels of the enable inputs.

SN54ALS161B, SN54ALS162B, SN54ALS163B, SN54AS161, SN54AS163 . . . J PACKAGE SN74ALS161B, SN74AS161, SN74AS163 . . . D OR N PACKAGE SN74ALS163B . . . D, DB, OR N PACKAGE (TOP VIEW)



SN54ALS161B, SN54ALS162B, SN54ALS163B, SN54AS161, SN54AS163 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

The clear function for the 'ALS161B and 'AS161 devices is asynchronous. A low level at the clear (\overline{CLR}) input sets all four of the flip-flop outputs low, regardless of the levels of the CLK, LOAD, or enable inputs. The clear function for the SN54ALS162B, 'ALS163B, and 'AS163 devices is synchronous, and a low level at CLR sets all four of the flip-flop outputs low after the next clock pulse, regardless of the levels of the enable inputs. This synchronous clear allows the count length to be modified easily by decoding the Q outputs for the maximum count desired. The active-low output of the gate used for decoding is connected to $\overline{\text{CLR}}$ to synchronously clear the counter to 0000 (LLLL).

The carry look-ahead circuitry provides for cascading counters for n-bit synchronous applications without additional gating. ENP and ENT inputs and a ripple-carry (RCO) output are instrumental in accomplishing this function. Both ENP and ENT must be high to count, and ENT is fed forward to enable RCO, RCO, thus enabled,



testing of all parameters.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include

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description (continued)

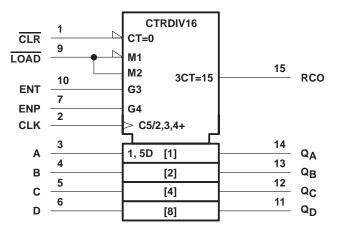
produces a high-level pulse while the count is maximum (9 or 15, with $Q_{\mbox{\scriptsize A}}$ high). The high-level overflow ripple-carry pulse can be used to enable successive cascaded stages. Transitions at ENP or ENT are allowed, regardless of the level of CLK.

These counters feature a fully independent clock circuit. Changes at control inputs (ENP, ENT, or LOAD) that modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) is dictated solely by the conditions meeting the stable setup and hold times.

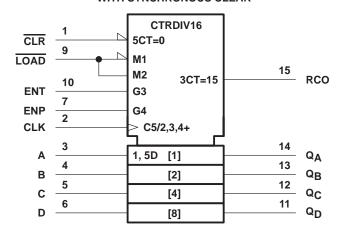
The SN54ALS161B, SN54ALS162B, SN54ALS163B, SN54AS161, and SN54AS163 are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS161B, SN74ALS163B, SN74AS161, and SN74AS163 are characterized for operation from 0°C to 70°C.

logic symbols†

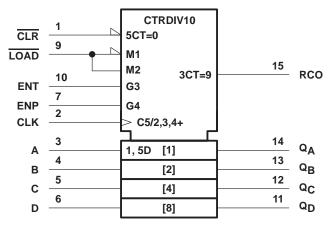
'ALS161B AND 'AS161 BINARY COUNTERS WITH DIRECT CLEAR



'ALS163B AND 'AS163 BINARY COUNTERS WITH SYNCHRONOUS CLEAR



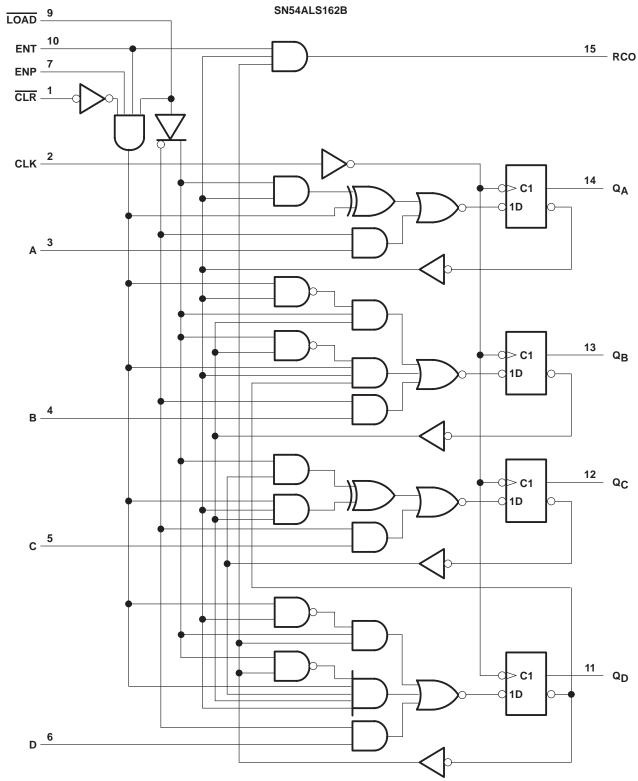
SN54ALS162B DECADE COUNTER WITH SYNCHRONOUS CLEAR



[†] These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, DB, J, and N packages.



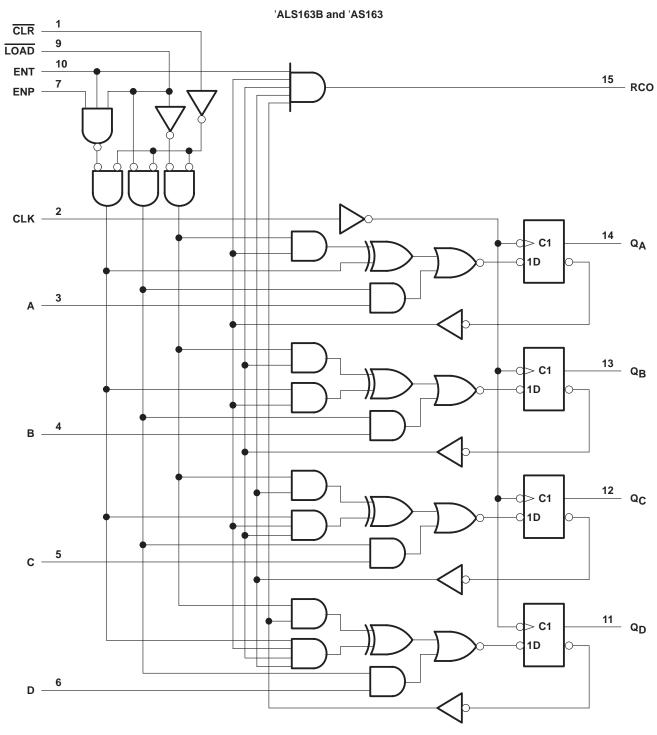
logic diagram (positive logic)



Pin numbers shown are for the J package.



logic diagram (positive logic)



Pin numbers shown are for the D, DB, J, and N packages.

'ALS161B and 'AS161 synchronous binary counters are similar; however, $\overline{\text{CLR}}$ is asynchronous.

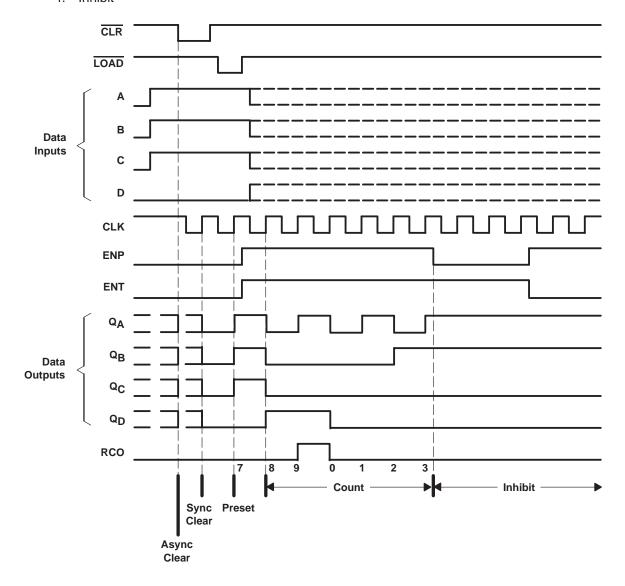


typical clear, preset, count, and inhibit sequences

SN54ALS162B

The following sequence is illustrated below:

- 1. Clear outputs to zero (SN54ALS162B is synchronous)
- 2. Preset to BCD 7
- 3. Count to 8, 9, 0, 1, 2, and 3
- 4. Inhibit

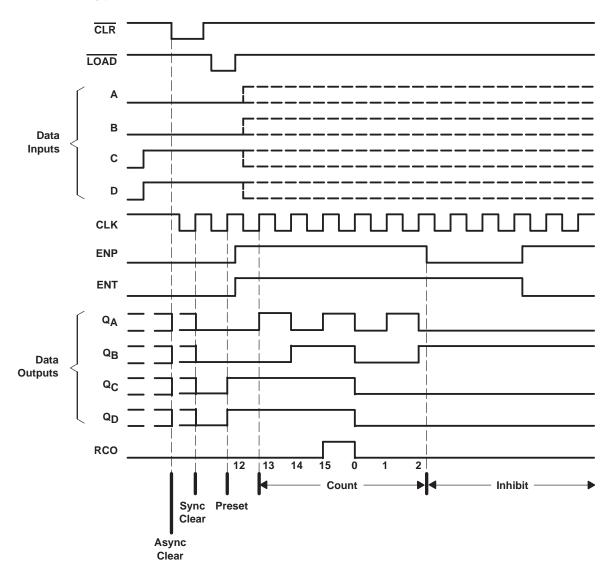


typical clear, preset, count, and inhibit sequences

'ALS161B, 'AS161, 'ALS163B, and 'AS163

The following sequence is illustrated below:

- 1. Clear outputs to zero ('ALS161B and 'AS161 are asynchronous; 'ALS163B and 'AS163 are synchronous.)
- 2. Preset to binary 12
- 3. Count to 13, 14, 15, 0, 1, and 2
- 4. Inhibit





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		0.5 V to 7 \
Input voltage range, V _I		0.5 V to 7 \
Package thermal impedance, θ_{JA} (see Note 1):	D package	73°C/V
	DB package	82°C/V
	N package	67°C/V
Storage temperature range, T _{stg}		−65°C to 150°C

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions

		SNS	SN54ALS161B SN54ALS162B SN54ALS163B		SN74ALS161B SN74ALS163B			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
ІОН	High-level output current			-0.4			-0.4	mA
loL	Low-level output current			4			8	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54ALS161B SN54ALS162B SN54ALS163B		SN74ALS161B SN74ALS163B			UNIT	
			MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V _{IK}	$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.5			-1.5	V
Voн	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	2		V
Voi	V _{CC} = 4.5 V	I _{OL} = 4 mA		0.25	0.4		0.25	0.4	V
VOL	VCC = 4.5 V	$I_{OL} = 8 \text{ mA}$					0.35	0.5	V
Ι _Ι	$V_{CC} = 5.5 V,$	V _I = 7 V			0.1			0.1	mA
lін	$V_{CC} = 5.5 V,$	V _I = 2.7 V			20			20	μΑ
Ι _Ι L	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.2			-0.2	mA
ΙΟ [§]	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
Icc	V _{CC} = 5.5 V			12	21		12	21	mA

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[§] The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, IOS.

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timing requirements over recommended operating conditions (unless otherwise noted) (see Figure 1)

				SN54ALS161B SN54ALS162B SN54ALS163B		B SN/4ALS161B		UNIT
				MIN	MAX	MIN	MAX	
fclock							40	MHz
	Pulse duration	CLR high or low		20		12.5		ns
t _W	Puise duration	'ALS161B	CLR low	20		15		115
		A, B, C, D	A, B, C, D			15		
		LOAD		20		15		
		'ALS161B	ENP, ENT	25		15		
t _{su}	Setup time, before CLK↑	SN54ALS162B, 'ALS163B	TENP, ENT	20		15		ns
		'ALS161B	CLR inactive	10		10		
		CNEAN CACOD IN CACOD	CLR low	20		15		
		SN54ALS162B, 'ALS163B	CLR high	20		10		
t _h	Hold time, all synchronous input	0		0		ns		

switching characteristics over recommended operating conditions (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	ТО	SN54AL	S161B	SN74ALS161B		UNIT
PARAWIETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	UNIT
f _{max}			22		40		MHz
^t PLH	CLK	RCO	5	34	5	20	ns
^t PHL	OLK	KCO	5	27	5	20	115
^t PLH	CLK	Any Q	4	19	4	15	ns
^t PHL	OLK		6	25	6	20	115
^t PLH	CNIT	RCO	3	18	3	13	ns
^t PHL	ENT	KCO	3	17	3	13	115
tou	CLR	Any Q	8	27	8	24	ns
^t PHL	CLR	RCO	11	32	11	23	115

switching characteristics over recommended operating conditions (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ALS162B SN54ALS163B		SN74AL	UNIT	
	(1141 01)	(001101)	MIN	MAX	MIN	MAX	
f _{max}			22		40		MHz
^t PLH	CLK	RCO	5	25	5	20	ns
^t PHL	OLK	NCO NCO	5	25	5	20	115
^t PLH	CLK	Any Q	4	18	4	15	ns
^t PHL	OLK	Ally Q	6	25	6	20	115
t _{PLH}	ENT	RCO	3	16	3	13	ns
^t PHL	LINI	INCO	3	16	3	13	110



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recommended operating conditions

		SN54AS161 SN54AS163			SN74AS161 SN74AS163			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.8			0.8	V
ІОН	High-level output current			-2			-2	mA
loL	Low-level output current			20			20	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

P/	ARAMETER	TEST CO	TEST CONDITIONS		SN54AS161 SN54AS163			174AS16 174AS16		UNIT
					TYP [†]	MAX	MIN	TYP [†]	MAX	
VIK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V
Vон		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	!		V
VOL		$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 20 \text{ mA}$		0.25	0.5		0.25	0.5	V
	LOAD					0.3			0.3	
l _l	ENT	$V_{CC} = 5.5 V,$	$V_I = 7 V$			0.2			0.2	mA
	All others	1				0.1			0.1	
	LOAD					60			60	
۱н	ENT	$V_{CC} = 5.5 V,$	$V_{I} = 2.7 \ V$			40			40	μΑ
	All others	1			•	20			20	
	LOAD					-1.5			-1.5	
Ι _Ι L	ENT	$V_{CC} = 5.5 V,$	$V_{I} = 0.4 \ V$			-1			-1	mA
	All others	1				-0.5			-0.5	
lo [‡]		V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	-30		-112	mA
ICC		V _{CC} = 5.5 V			35	53		35	53	mA

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, los.

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timing requirements over recommended operating conditions (see Figure 1)

				SN54AS161 SN54AS163		SN74AS161 SN74AS163		UNIT
				MIN	MAX	MIN	MAX	
fclock	Clock frequency				65		75	MHz
	Pulse duration	CLR high or low		7.7		6.7		no
t _W	Puise duration	'AS161	CLR low	10		8		ns
		A, B, C, D		10		8		
		LOAD		10		8		
l.	Satura tima hafara CLKA	ENP, ENT		10		8		
t _{su}	Setup time, before CLK↑	'AS161	CLR inactive	10		8		ns
		'AS163	CLR low	14		12		
		A3103	CLR high (inactive)	10		9		
t _h	Hold time, all synchronous input	s after CLK↑		2		0		ns

switching characteristics over recommended operating conditions (see Figure 1)

PARAMETER	FROM	то	SN54A	S161	SN74A	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	UNII
f _{max}			65*		75		MHz
+ 5	CLK	RCO (with LOAD high)	1	8.5	1	8	20
^t PLH	OLK	RCO (with LOAD low)	3	17.5	3	16.5	ns
^t PHL	CLK	RCO	2	14	2	12.5	ns
^t PLH	CLK	A O	1	7.5	1	7	20
^t PHL	CLK	Any Q	2	14	2	13	ns
^t PLH	ENIT	RCO	1.5	10	1.5	9	ns
^t PHL	ENT	, KCO	1	9.5	1	8.5	115
to	CLR	Any Q	2	14	2	13	ns
^t PHL	CLR	RCO	2	14	2	12.5	115

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

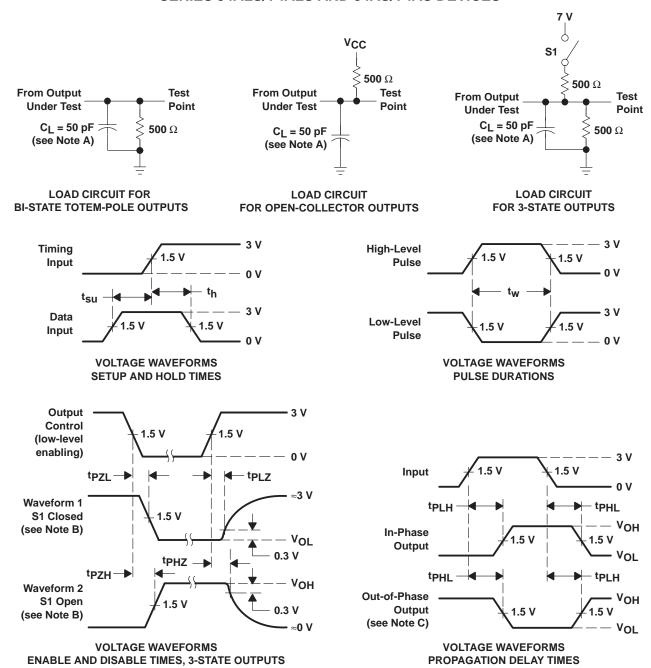
switching characteristics over recommended operating conditions (see Figure 1)

PARAMETER	FROM	то	SN54A	SN54AS163		SN74AS163		
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	UNIT	
f _{max}			65*		75		MHz	
t	CLK	RCO (with LOAD high)	1	8.5	1	8	ns	
^t PLH	CLK	RCO (with LOAD low)	3	17.5	3	16.5	115	
t _{PHL}	CLK	RCO	2	14	2	12.5	ns	
t _{PLH}	CLK	Any Q	1	7.5	1	7	ns	
t _{PHL}	CLK	Ally Q	2	14	2	13	115	
t _{PLH}	ENT	RCO	1.5	10	1.5	9	ne	
t _{PHL}	LINI	NOO	1	9.5	1	8.5	ns	

 $^{^{\}star}$ On products compliant to MIL-PRF-38535, this parameter is not production tested.



PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: $PRR \le 1$ MHz, $t_f = t_f = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



APPLICATION INFORMATION

n-bit synchronous counters

This application demonstrates how the ripple-mode carry circuit (see Figure 2) and the carry look-ahead circuit (see Figure 3) can be used to implement a high-speed n-bit counter. The SN54ALS162B counts in BCD. The 'ALS161B, 'AS161, 'ALS163B, and 'AS163 devices count in binary. When additional stages are added, the f_{max} decreases in Figure 2, but remains unchanged in Figure 3.

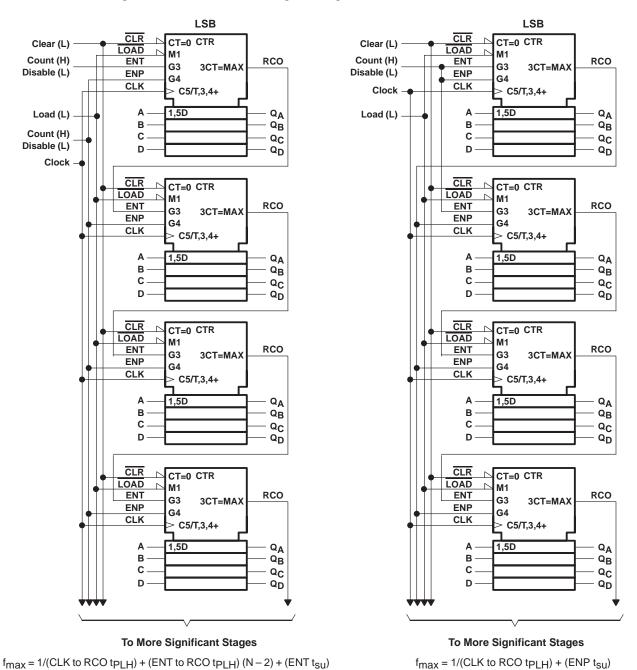


Figure 2. Ripple-Mode Carry Circuit

Figure 3. Carry Look-Ahead Circuit



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
83022012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8302201EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
8302201FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
83022022A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8302202EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
8302202FA	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI
JM38510/38001B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/38001BEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/38002B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/38002BEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54ALS161BJ	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54ALS163BJ	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54AS161J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54AS163J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN74ALS161BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS161BDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS161BDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS161BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS161BDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS161BDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS161BN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS161BN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74ALS161BNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS161BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS161BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS163BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS163BDBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS163BDBRE4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS163BDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS163BDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS163BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM





om 23-Apr-2007

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ALS163BDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS163BDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS163BN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS163BN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74ALS163BNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS163BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS163BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS161D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS161DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS161DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS161DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS161DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS161DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS161N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS161NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS161NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS161NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS163D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS163DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS163DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS163DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS163DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS163DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS163N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS163NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS163NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM



PACKAGE OPTION ADDENDUM

23-Apr-2007

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AS163NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54ALS161BFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54ALS161BJ	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54ALS161BW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54ALS163BFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54ALS163BJ	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54AS161FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54AS161J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54AS163J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

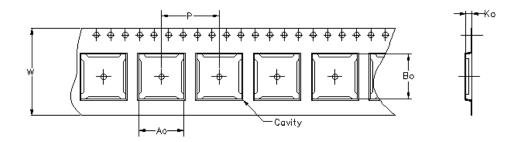
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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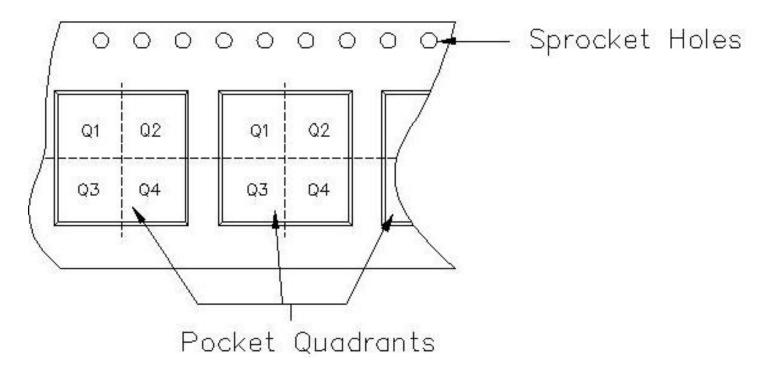
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Carrier tape design is defined largely by the component lentgh, width, and thickness.

Ao =	Dimension	designed	to	accommodate	the	component	width.		
Bo =	Dímension	designed	to	accommodate	the	component	length.		
Ko =	Dímension	designed	to	accommodate	the	component	thickness.		
W =	Overall widt	h of the	car	rier tape.					
P = 1	P = Pitch between successive cavity centers.								

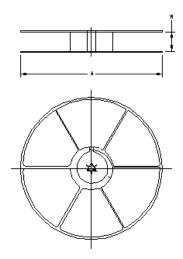


TAPE AND REEL INFORMATION



30-Apr-2007

Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS161BDR	D	16	FMX	0	16	6.5	10.3	12.1	2	16	Q1
SN74ALS161BNSR	NS	16	MLA	330	16	8.2	10.5	2.5	12	16	Q1
SN74ALS163BDBR	DB	16	MLA	330	16	8.2	6.6	2.5	12	16	Q1
SN74ALS163BDR	D	16	FMX	0	16	6.5	10.3	12.1	2	16	Q1
SN74ALS163BNSR	NS	16	MLA	330	16	8.2	10.5	2.5	12	16	Q1
SN74AS161DR	D	16	FMX	0	16	6.5	10.3	12.1	2	16	Q1
SN74AS161NSR	NS	16	MLA	330	16	8.2	10.5	2.5	12	16	Q1
SN74AS163DR	D	16	FMX	0	16	6.5	10.3	12.1	2	16	Q1
SN74AS163NSR	NS	16	MLA	330	16	8.2	10.5	2.5	12	16	Q1



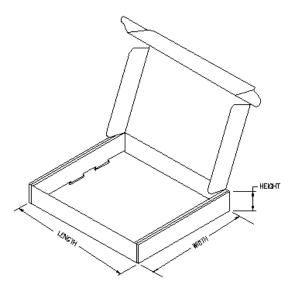
TAPE AND REEL BOX INFORMATION

Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74ALS161BDR	D	16	FMX	333.2	333.2	28.58
SN74ALS161BNSR	NS	16	MLA	333.2	333.2	28.58
SN74ALS163BDBR	DB	16	MLA	333.2	333.2	28.58
SN74ALS163BDR	D	16	FMX	333.2	333.2	28.58
SN74ALS163BNSR	NS	16	MLA	333.2	333.2	28.58
SN74AS161DR	D	16	FMX	333.2	333.2	28.58
SN74AS161NSR	NS	16	MLA	333.2	333.2	28.58
SN74AS163DR	D	16	FMX	333.2	333.2	28.58
SN74AS163NSR	NS	16	MLA	333.2	333.2	28.58





30-Apr-2007



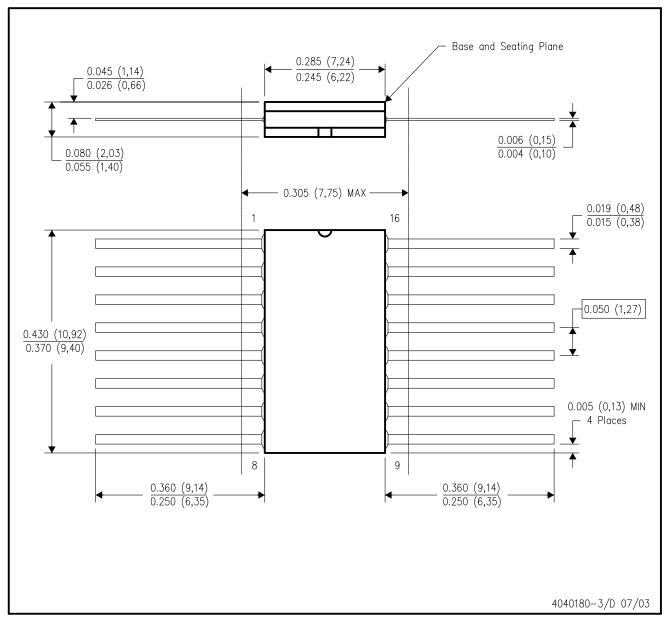
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

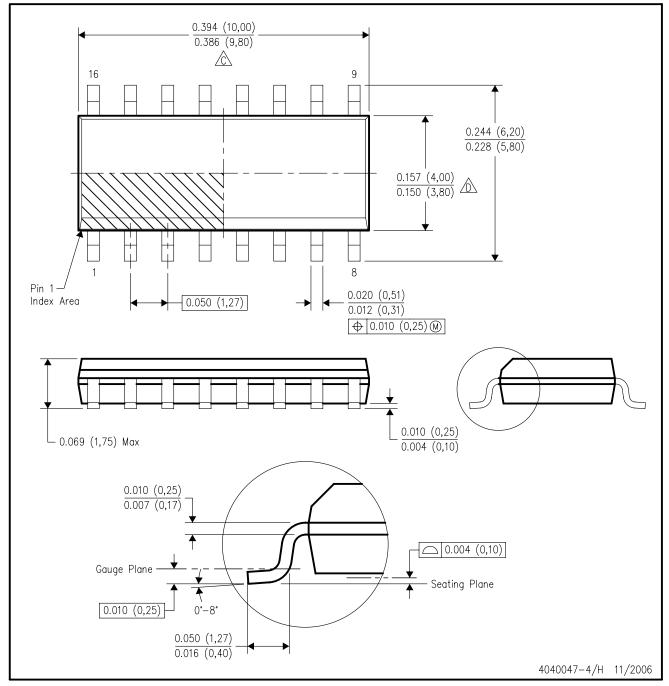


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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